



Material Content Data Sheet



Sales Product Name		XMC1301-T016F0032 AB		Issued		7. August 2015		
MA#		MA001403214						
Package		PG-TSSOP-16-8		Weight*		61.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.226	1.98	1.98	19823	19823
leadframe	inorganic material	phosphorus	7723-14-0	0.007	0.01		109	
	non noble metal	zinc	7440-66-6	0.027	0.04		434	
	non noble metal	iron	7439-89-6	0.537	0.87		8687	
wire	non noble metal	copper	7440-50-8	21.811	35.27	36.19	352748	361978
	noble metal	palladium	7440-05-3	0.001	0.00		21	
	non noble metal	copper	7440-50-8	0.130	0.21	0.21	2104	2125
encapsulation	organic material	carbon black	1333-86-4	0.108	0.18		1755	
	plastics	epoxy resin	-	4.231	6.84		68434	
	inorganic material	silicondioxide	60676-86-0	31.825	51.48	58.50	514717	584906
leadfinish	non noble metal	tin	7440-31-5	0.926	1.50	1.50	14980	14980
plating	noble metal	silver	7440-22-4	0.558	0.90	0.90	9020	9020
glue	plastics	epoxy resin	-	0.111	0.18		1792	
	noble metal	silver	7440-22-4	0.332	0.54	0.72	5376	7168
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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